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Fairchild Semiconductor FDA33N25

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May 2014

#### **FDA33N25**

# N-Channel UniFET<sup>TM</sup> MOSFET 250 V, 33 A, 94 m $\Omega$

#### **Features**

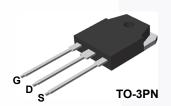
- $R_{DS(on)}$  = 88 m $\Omega$  (Typ.) @  $V_{GS}$  = 10 V,  $I_D$  =16.5 A
- · Low Gate Charge (Typ. 36 nC)
- Low C<sub>rss</sub> (Typ. 35 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

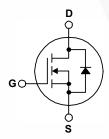
#### **Applications**

- PDP TV
- · Uninterruptible Power Supply
- AC-DC Power Supply

#### **Description**

UniFET<sup>TM</sup> MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





#### **MOSFET Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FDA33N25	Unit	
V <sub>DSS</sub>	Drain to Source Voltage			250	V	
V <sub>GSS</sub>	Gate to Source Voltage			±30	V	
,	- Continuous (T <sub>C</sub> = 25°C)			33		
ID	Drain Current	- Continuous (T <sub>C</sub> = 100°C)		21	Α	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	132	Α	
E <sub>AS</sub>	Single Pulsed Avalanche	e Energy	(Note 2)	918	mJ	
I <sub>AR</sub>	Avalanche Current		(Note 1)	33	Α	
E <sub>AR</sub>	Repetitive Avalanche En	ergy	(Note 1)	24.6	mJ	
dv/dt	Peak Diode Recovery dv	r/dt	(Note 3)	4.5	V/ns	
n	Dawer Dissination	(T <sub>C</sub> = 25°C)		245	W	
$P_{D}$	Power Dissipation	- Derate Above 25°C		1.96	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage T	emperature Range		-55 to +150	οС	
Tı	Maximum Lead Tempera	ture for Soldering, 1/8" from Case for 5 Se	conds	300	οС	

#### **Thermal Characteristics**

Symbol	Parameter	FDA33N25	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.51	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	



## Datasheet of FDA33N25 - MOSFET N-CH 250V 33A TO-3PN

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#### **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDA33N25	FDA33N25	TO-3PN	Tube	N/A	N/A	30 units

#### **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 25^{\circ} C$	250	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C	-	0.34	-	V/°C
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V	-	-	1	μА
IDSS	Zero Gate Voltage Drain Gurrent	$V_{DS} = 200 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μΛ
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	-	-	±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	٧
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 16.5 \text{ A}$	-	0.088	0.094	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 16.5 A	-	24.2	-	S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V - 25 V V - 2 V		-	1655	2200	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		-	315	420	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1/1/12		-\	35	55	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 200 V, I <sub>D</sub> = 33 A,		- \	36	46.8	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V		- \	10.8	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		(Note 4)	-	16	-	nC

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	33	76	ns
t <sub>r</sub>		$V_{DD} = 125 \text{ V}, I_D = 33 \text{ A},$	-	142	293	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_G$ = 25 $\Omega$	-	77	165	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	68	146	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	33	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	132	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 33 A	-	-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 33 A,	-	256	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	2.3	_	μC

#### Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 1.35 mH, I  $_{AS}$  = 33 A, V  $_{DD}$  = 50 V, R  $_{G}$  = 25  $\Omega,$  starting T  $_{J}$  = 25  $^{\circ}C.$
- 3.  $I_{SD} \le 33$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , starting  $T_J$  = 25°C.
- 4. Essentially independent of operating temperature typical Characteristics



## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

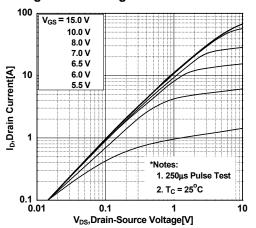


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage** 

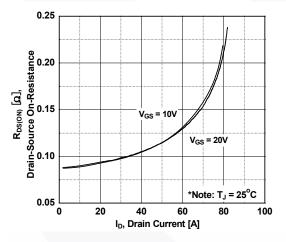


Figure 5. Capacitance Characteristics

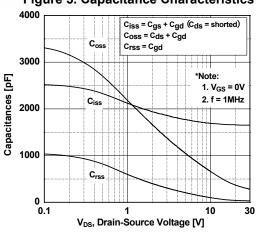


Figure 2. Transfer Characteristics

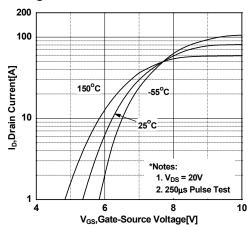


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

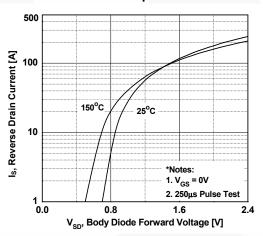
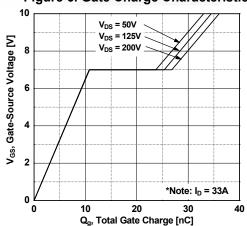


Figure 6. Gate Charge Characteristics





#### **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

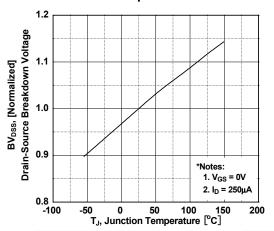


Figure 8. On-Resistance Variation vs. Temperature

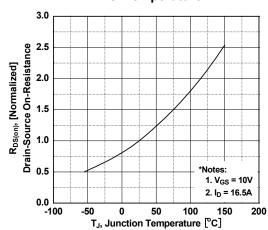


Figure 9. Maximum Safe Operating Area

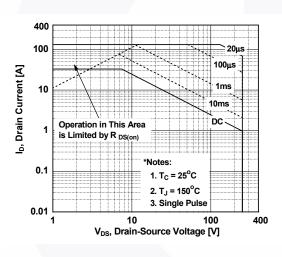


Figure 10. Maximum Drain Current vs. Case Temperature

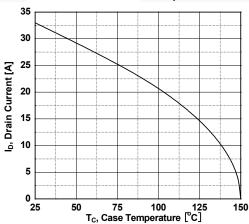
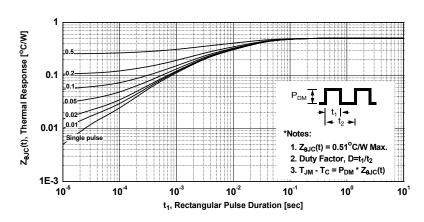


Figure 11. Transient Thermal Response Curve



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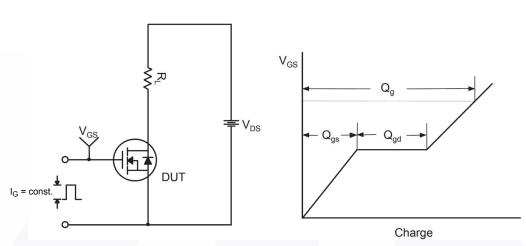


Figure 12. Gate Charge Test Circuit & Waveform

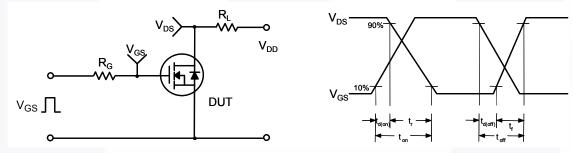


Figure 13. Resistive Switching Test Circuit & Waveforms

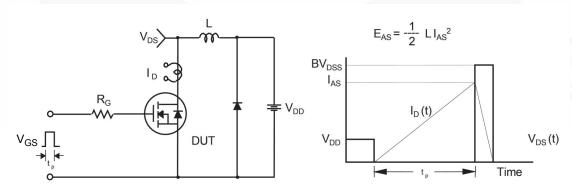
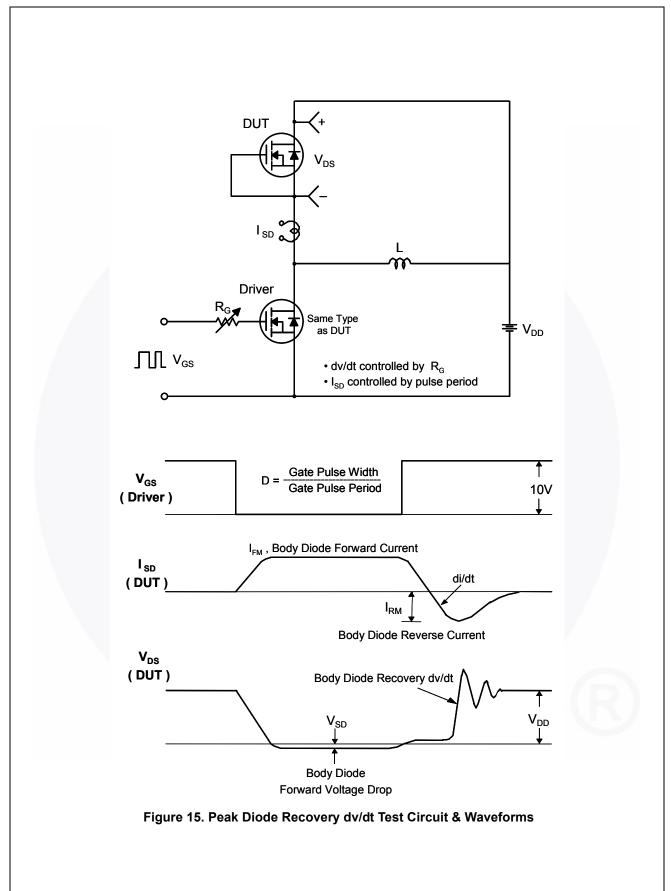
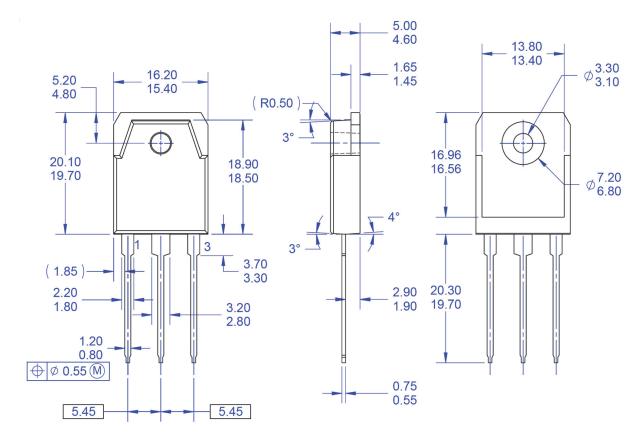
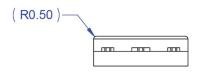


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



#### **Mechanical Dimensions**





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ
- SC-65 PACKAGING STANDARD.
  ALL DIMENSIONS ARE IN MILLIMETERS.
  DIMENSION AND TOLERANCING PER
  ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS. DRAWING FILE NAME: TO3PN03AREV1.
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Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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